

LQ-BLB100-ER1C

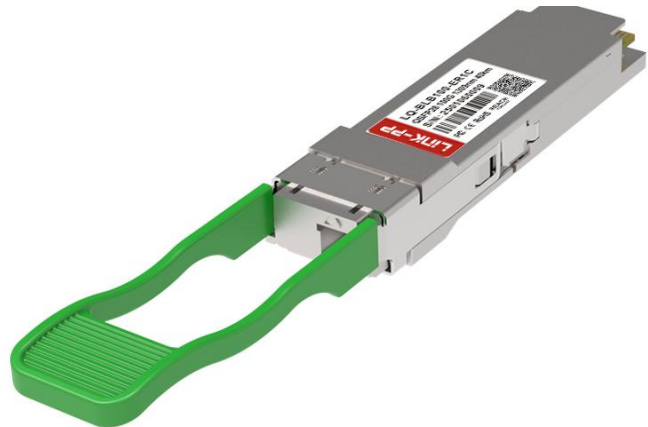
100Gb/s QSFP28 BIDI ER1 40km DDM Transceiver

Product Features

- Supports 100GBASE-ER BIDI;
- Lane signaling rate 106.25 Gb/s with PAM4;
- Up to 40km transmission on SMF;
- EML TOSA and APD ROSA;
- 4x25.78Gb/s with NRZ electrical interface (CAUI-4);
- High speed I/O electrical interface ;
- I2C interface with integrated Digital Diagnostic monitoring;
- QSFP28 MSA package with simplex LC connector;
- Single +3.3V power supply;
- Maximum power consumption 4.5 W;
- Operating case temperature: 0 to +70 °C;
- Compliant to 802.3cu, SFF-8636&SFF-8679 standard;
- Complies with EU Directive 2015/863/EU.

Applications

- Data Center Interconnect
- 100GBASE-ER1 BIDI



Absolute Maximum Ratings

Parameter	Symbol	Min.	Typical	Max.	Unit	Notes
Storage Temperature	TS	-40		+85	°C	
Supply Voltage	VCC	-0.5		+4.0	V	
Operating Relative Humidity	RH			+85	%	

Recommended Operating Conditions

Parameter	Symbol	Min.	Typical	Max.	Unit	Notes
Operating Case Temperature	TC	0		+70	°C	
Power Supply Voltage	VCC	3.13	3.3	3.47	V	
Transmission Distance	TD			10	km	Over SMF

Optical and Characteristics

Parameter	Symbol	Min.	Typical	Max.	Unit	Notes
Transmitter						
Center Wavelength	CW	1304.06	1304.58	1305.1	nm	
		1308.61	1309.14	1309.66	nm	
Signaling Rate	SR			53.125	GBd	
Frequency Offset	Foffset	-100		100	ppm	
Average Launch Power	PTX	1.5	-	7.1	dBm	1
Outer Optical Modulation Amplitude (OMA _{outer}) (min) for TDECQ < 1.4 dB for 1.4 dB ≤ TDECQ ≤ TDECQ (max)	OMA _{outer}	4.5	-	7.9	dBm	TDECQ < 1.4 dB
		3.1+TDECQ	-		dBm	TDECQ > 1.4 dB
Transmitter and dispersion eye closure for PAM4 (TDECQ) (max)	TDECQ			3.9	dBm	

Average Output Power (Laser Turn	Poff			-30	dBm	
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off)						
Side Mode Suppression Ratio	SMSR	30			dB	
Extinction Ratio	ER	6			dB	
RIN_OMA	RIN			-136	dB/Hz	
Transmitter reflectance	Tref			-26	dB	
Optical Return Loss Tolerance	ORLT			15.6	dB	
Receiver						
Center Wavelength	CW	1308.61	1309.14	1309.66	nm	
		1304.06	1304.58	1305.1	nm	
Damage threshold	Pdamage	-2.4			dBm	2
Average Rx Power	PRx	-16.2	-	-3.4	dBm	3
Receive power _OMOuter	POMA			-2.6	dBm	
Receiver sensitivity _OMOuter for TDECQ < 1.4 dB for 1.4 dB ≤ TDECQ ≤ 3.4 dB	SEN_OMA			-14 -15.4+TECQ	dBm	4
Reflectance	Ref			-26	dB	
Los Assert	LosA	-30			dBm	
Los De-Assert	LosDA			-18	dBm	
Los Hysteresis	LosH	0.5			dB	

Notes:

1. The optical power is launched into SMF.
2. The receiver shall be able to tolerate, without damage, continuous exposure to an optical input signal having this average power level. The receiver does not have to operate correctly at this input power.
3. Average receive power, each lane (min) is informative and not the principal indicator of signal strength.
4. Measured with conformance test signal at TP3 using the test pattern PRBS31Q or scrambled idle for stressed receiver sensitivity for the BER= 2.4x10⁻⁴.
5. Measured with conformance test signal at TP3 (see3.11) for the BER specified in IEEE Std 802.3cu

Parameter	Symbol	Min.	Typical	Max.	Unit	Notes
Transmitter (Module Input)						
Input Differential Impedance	Rin		100		Ohm	
Differential Data Input Amplitude	VIN,P-P	80		900	mVpp	
Differential termination mismatch (max)	D-mismatch			10	%	
DC common-mode input voltage		-0.3		2.8	V	
Transition time(20%~80%)	Tr Tf	10			ps	
LPMode, Reset and ModSelL / Tx dis	VIL	-0.3		0.8	V	
LPMode, Reset and ModSelL / Tx dis	VIH	2.0		VCC+0.3	V	
Receiver (Module Output)						
Output Differential Impedance	Rout		100		Ohm	
Differential Data Output Amplitude	VOU TP-P			900	mVpp	
Differential termination mismatch (max)	D-mismatch			10	%	
Transition time, 20% to 80%	Tr Tf	12			ps	
ModPrsL and IntL/ Rx los	VOL	0		0.4	V	
ModPrsL and IntL/ Rx los	VOH	VCC-0.5		VCC+0.3	V	

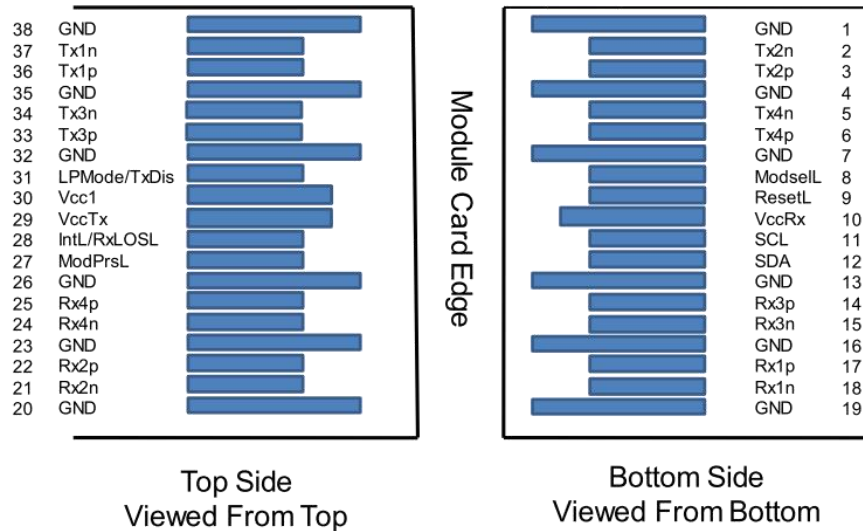
Digital Diagnostics

Parameter	Range	Accuracy	Unit	Calibration
Temperature	0 to 70	±3	°C	Internal
Voltage	0 to Vcc	±3%	V	Internal
Tx Bias Current	0 to 100	±10%	mA	Internal
Tx Output Power	-1.4 to 4.5	±3	dB	Internal
Rx Input Power	-7.7 to 4.5	±3	dB	Internal

Communication Interface Timing Characteristics

Parameter	Symbol	Min	Max	Unit	Calibration	Notes
Initialization time	t_init		10	s	Time from power on or hot plug until the module is fully functional. This time applies to Power Class 2 or higher modules when LPMode is pulled low by the host, and to all Power Class 1 modules.	Room Temperature

Pin Diagram



Pin Definitions

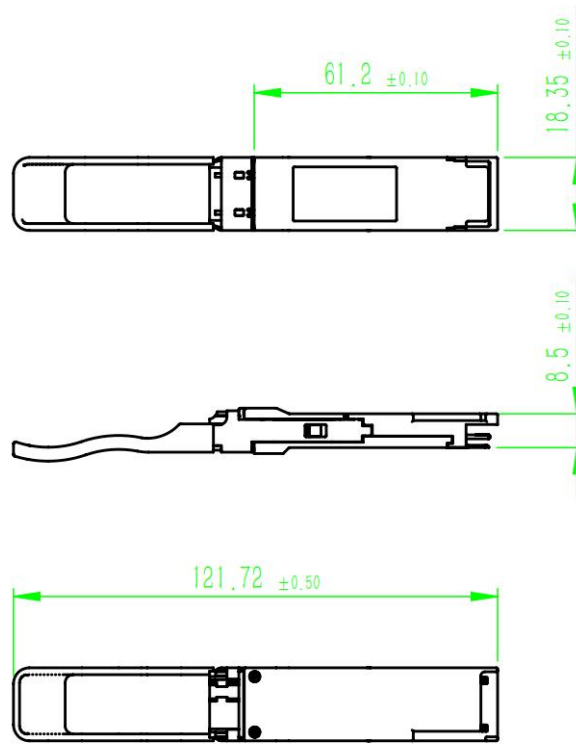
PIN	Logic	Symbol	Description	Plug Seq.	Notes
1		GND	Ground	1	1
2	CML-I	Tx2n	Transmitter Inverted Data Input	3	
3	CML-I	Tx2p	Transmitter Non-Inverted Data output	3	
4		GND	Ground	1	1
5	CML-I	Tx4n	Transmitter Inverted Data Input	3	
6	CML-I	Tx4p	Transmitter Non-Inverted Data output	3	
7		GND	Ground	1	1
8	LVTLL-I	ModSelL	Module Select	3	
9	LVTLL-I	ResetL	Module Reset	3	

10		VccRx	+ 3.3V Power Supply Receiver	2	2
11	LVC MOS-I/O	SCL	2-Wire Serial Interface Clock	3	
12	LVC MOS-I/O	SDA	2-Wire Serial Interface Data	3	
13		GND	Ground	1	
14	CML-O	Rx3p	Receiver Non-Inverted Data Output	3	
15	CML-O	Rx3n	Receiver Inverted Data Output	3	
16		GND	Ground	1	1
17	CML-O	Rx1p	Receiver Non-Inverted Data Output	3	
18	CML-O	Rx1n	Receiver Inverted Data Output	3	
19		GND	Ground	1	1
20		GND	Ground	1	1
21	CML-O	Rx2n	Receiver Inverted Data Output	3	
22	CML-O	Rx2p	Receiver Non-Inverted Data Output	3	
23		GND	Ground	1	1
24	CML-O	Rx4n	Receiver Inverted Data Output	3	1
25	CML-O	Rx4p	Receiver Non-Inverted Data Output	3	
26		GND	Ground	1	1
27	LVTTL-O	ModPrsL	Module Present	3	
28	LVTTL-O	IntL/Rx_LOS	Interrupt/Rx_LOS	3	3
29		VccTx	+3.3 V Power Supply transmitter	2	2
30		Vcc1	+3.3 V Power Supply	2	2
31	LVTTL-I	LPMode/TxDIS	Low Power Mode/Tx_Disable	3	3
32		GND	Ground	1	1
33	CML-I	Tx3p	Transmitter Non-Inverted Data Input	3	
34	CML-I	Tx3n	Transmitter Inverted Data Output	3	
35		GND	Ground	1	1
36	CML-I	Tx1p	Transmitter Non-Inverted Data Input	3	
37	CML-I	Tx1n	Transmitter Inverted Data Output	3	
38		GND	Ground	1	1

Notes:

1. GND is the symbol for signal and supply (power) common for the QSFP28 module. All are common within the QSFP28 module and all module voltages are referenced to this potential unless otherwise noted. Connect these directly to the host board signal-common ground plane.
2. Vcc Rx, Vcc1 and Vcc Tx are the receiver and transmitter power supplies and shall be applied concurrently. Requirements defined for the host side of the Host Edge Card Connector are listed in MSA. The connector pins are each rated for a maximum current of 1000 mA.
3. Two Multi-Purpose Pin for supporting Tx_DIS and Rx_LOS function in the 100G QSFP28 LR1 BIDI module.

Mechanical Specifications



Ordering information

Part Number	Product Description
LQ-BLA100-ER1C	1304T/1309R, 106.25Gbps, LC,40km, 0°C~+70°C
LQ-BLB100-ER1C	1309T/1304R, 106.25Gbps, LC, 40km, 0°C~+70°C